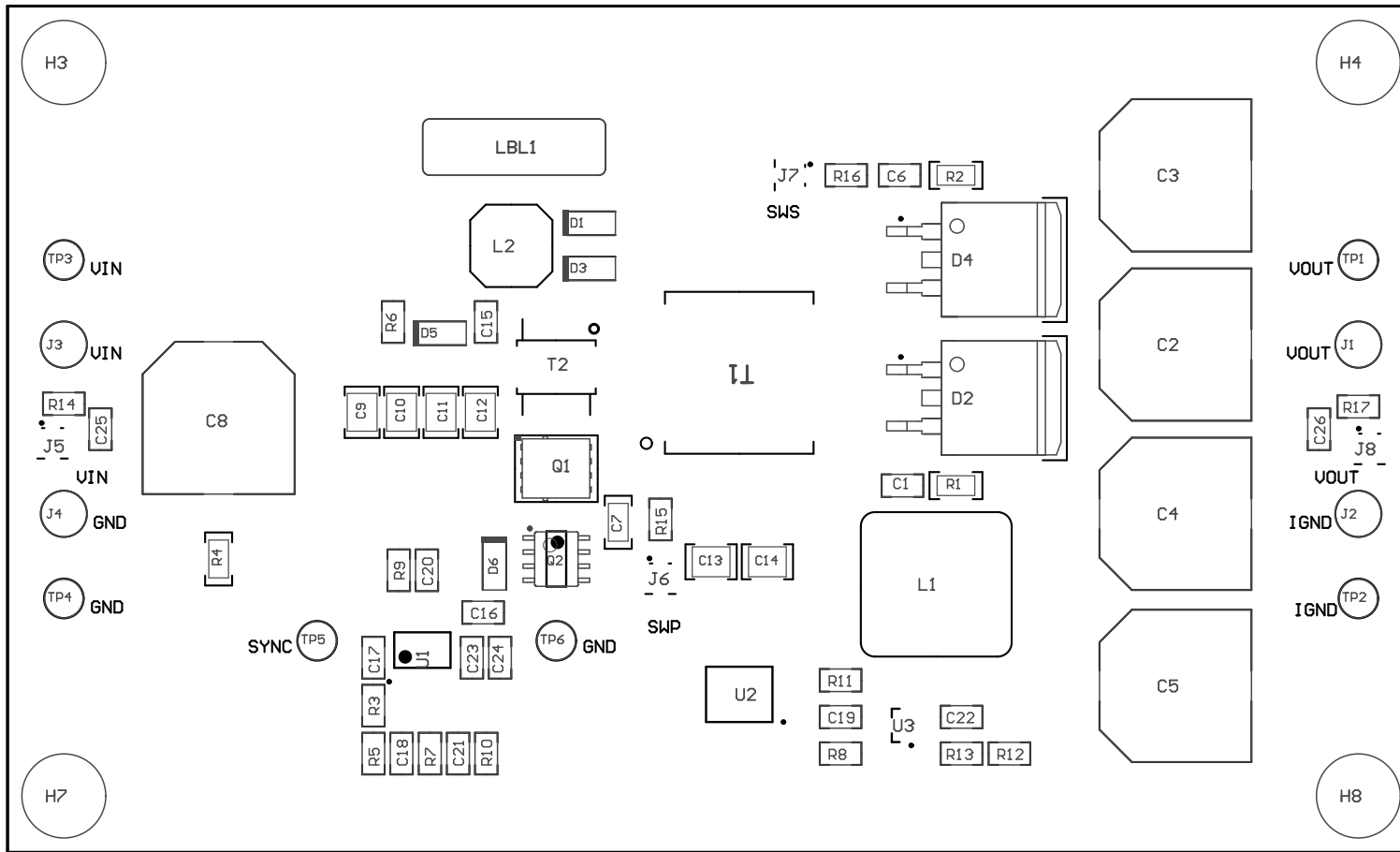


Z21 ■Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per Table 1

Z22 ■These assemblies are ESD sensitive, ESD precautions shall be observed.

Z23 ■These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

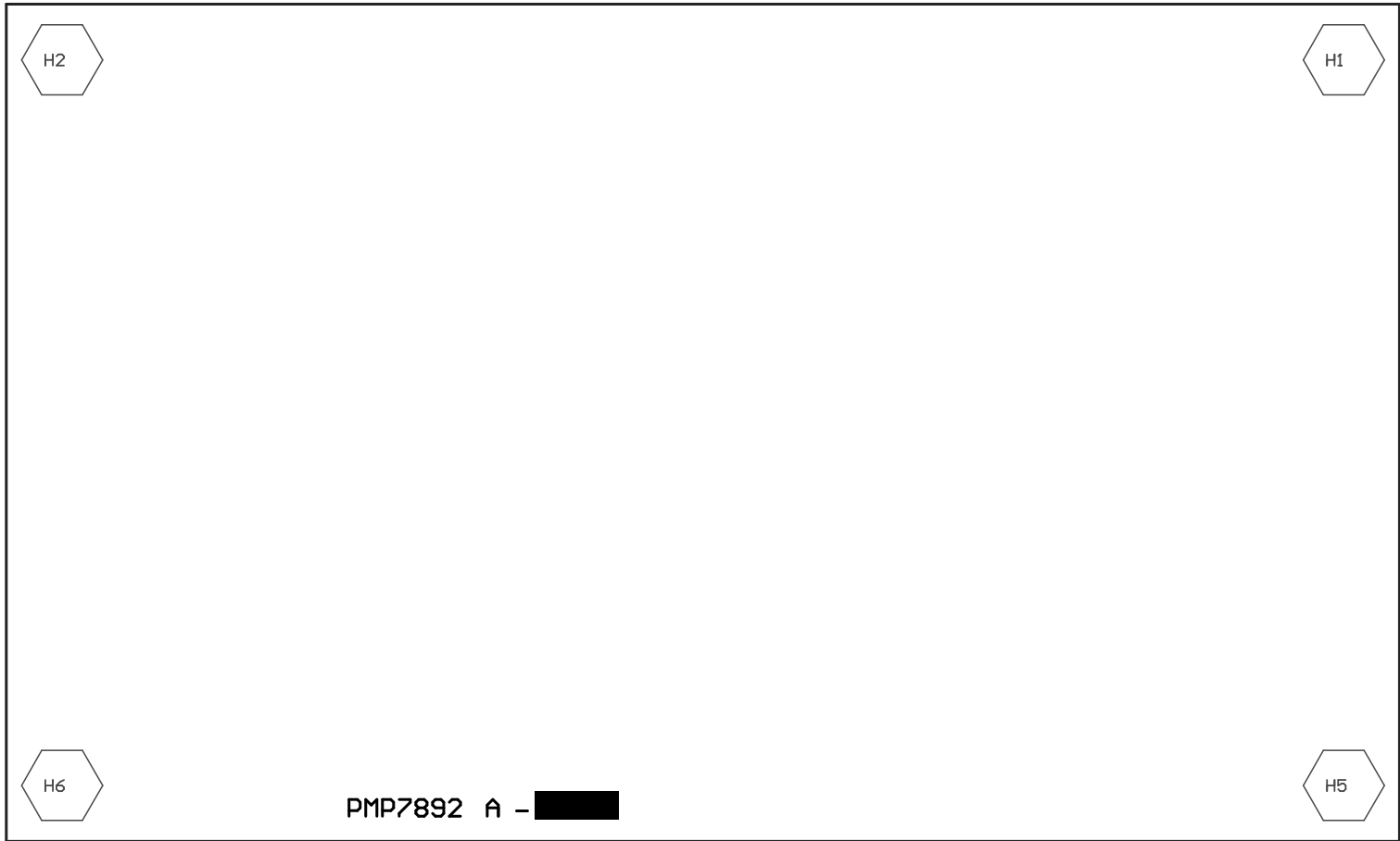
Z24 ■These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.



Variant	Label text
001	ChangeMe!
002	ChangeMe!

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP7892	REV: A	SUN REV: Not In VersionControl
IGNORE -> Top Overlay			
PLOT NAME = Top Assembly Drawing	GENERATED : 12/17/2012 4:40:29 PM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP7892	REV: A	SUN REV: Not In VersionControl
	IGNORE -> Bottom Overlay		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 12/17/2012 4:40:30 PM	TEXAS INSTRUMENTS	

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